

Attachment No. 2

Minutes of the CE-2.2 Subcommittee on Sockets 16 – 17 April 2007 San Diego, CA

Facilitator Carl Fritz welcomed everyone, and said that the meeting would be conducted following the published agenda.

It is noted that all actions taken by the subcommittee will be simultaneously approved by the CE-2.0 committee.

1. Approval of the 28 – 29 September 2006 Minutes

The minutes of the 28 - 29 September 2006 meeting in Reno, NV were approved. Moved by Bob Druckenmiller and seconded by Ralph Antonelli. The motion was unanimously moved and approved.

2. SPECIFICATIONS BY PROJECT NUMBERS

A. SP-4965: Rev. EIA-540B0AE: Detail Land Grid Array (Contech Research is sponsor)

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

B. SP-4970: EIA-540DAAA-A: Detail, DIP

It was reported that the specification is at EDEC for approval.

C. SP-4971: EIA-700A0AB: 68-pin Memory Card Connector

It was reported that the specification is at EDEC for approval.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

E. SP-4982-1: EIA-5400000-A: Generic

Carl Fritz reported that the standard was published as reaffirmed 1 March 2007. Received FedEx 15 March 2007.

Attachment No. 2

F. SP-5055: Replacement document for EIA-676-A Detail, SFF 1.8 inch (45.7 mm) Disk Drives

It was reported that the standard published June 2006.

G. SP-5056: EIA-674: Detail, SFF 1.8" Disk Drives

It was reported that the standard was published August 2006.

H. SP-5058-A: EIA-720-A: Detail, SFF 2.5" Disk Drives

Carl Fritz reported that the standard was published February 2007 and received by FedEx on March 2007.

I. SP-5059: EIA-677: Detail, SFF Power Connector Pin Dimensions

Carl Fritz reported that the standard was published as reaffirmed 4 August 2006.

J. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

It was reported that a second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

Attachment No. 2

K. SP-5114 as follows:

- 540C000: Sectional Relay Sockets
- 540CA00: Blank, Relay Sockets
- 540CAAA: Detail, 10A Relay Socket
- 540CAAB: Detail, 5A Relay Socket

Carl Fritz reported that the standards were published as reaffirmed 1 March 2007 and received by FedEx on 15 March 2007.

L. PN-5123, EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

John Healey expressed his concern that it should be part of TS-1000. John will discuss the proposed standard with Tom Peel. Members were also requested to determine if they are currently using EIA-540B0AE and EIA-540B0AB, or are aware of any customer or supplier requirements that are using it. If they are not being used then why should they not be cancelled?

3. SPECIFICATIONS AWAITING PROJECT NUMBERS

4. NEW BUSINESS

There was no new business.

Prepared by:

Carl Fritz, Facilitator, CE-2.9